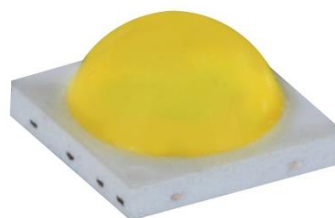


Superior high Flux for High Voltage System

## Acrich MJT– 4040 Series

SAWx9D0A



**LM-80**



## Product Brief

### Description

- The MJT series of LEDs are designed for AC & DC(High Voltage) operation and high flux output applications.
- MJT's thermal management performance exceeds other power LED solutions by incorporating state-of-the-art SMD design and use of specialized thermal emission material. MJT is an ideal light source for general purpose illumination applications.

### Features and Benefits

- Multi Junction Technology chips for high voltage operation
- 6.03V typical forward voltage @200mA
- Dimension : 4.0x4.0x2.2mm
- SMT solderable

### Key Applications

- Architectural
- Retail Display
- Commercial
- Industrial - High/Low bay
- Outdoor area - Street & tunnel light
- Parking light
- Off-grid
- Safety & Security

**Table 1. Product Selection Table**

| Part Number | CCT        |     |       |       |       |
|-------------|------------|-----|-------|-------|-------|
|             | Color      | CRI | Min.  | Typ.  | Max.  |
| SAW09D0A    | Cool White | 70  | 4700K | 5600K | 7000K |
| SAW89D0A    | Cool White | 80  | 4700K | 5600K | 7000K |

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## Performance Characteristics

**Table 2. Characteristics,  $I_F=200\text{mA}$  ,  $T_j=25^\circ\text{C}$ , RH30%**

| Parameter                                   | Symbol                  | Value                  |      |       | Unit               |
|---------------------------------------------|-------------------------|------------------------|------|-------|--------------------|
|                                             |                         | Min.                   | Typ. | Max.  |                    |
| Forward Current                             | $I_F$                   | -                      | 200  | 250   | mA                 |
| Forward Voltage                             | $V_F$                   | 5.6                    | 6.03 | 6.8   | V                  |
| Luminous Flux <sup>[1]</sup>                | $\Phi_V$ <sup>[2]</sup> | -                      | 215  | -     | lm                 |
| Correlated Color Temperature <sup>[3]</sup> | CCT                     | 4,700                  | -    | 7,000 | K                  |
| Color Rendering Index <sup>[4]</sup>        | $R_a$                   | 70                     | -    | -     | -                  |
| Viewing Angle                               | $2\theta_{1/2}$         | -                      | 120  | -     | deg.               |
| Peak Pulsed Forward Current <sup>[6]</sup>  | $I_{FP}$                | -                      | -    | 350   | mA                 |
| Power Dissipation                           | $P_D$                   | -                      | -    | 1.7   | W                  |
| Junction Temperature                        | $T_j$                   | -                      | -    | 125   | $^\circ\text{C}$   |
| Operating Temperature                       | $T_{opr}$               | - 40                   | -    | + 85  | $^\circ\text{C}$   |
| Storage Temperature                         | $T_{stg}$               | - 40                   | -    | + 100 | $^\circ\text{C}$   |
| Thermal resistance (J to S) <sup>[5]</sup>  | $R\theta_{J-S}$         | -                      | 7    | 12    | $^\circ\text{C/W}$ |
| ESD Sensitivity (HBM)                       | -                       | Class 3A JESD22-A114-E |      |       |                    |

### Notes :

[1] Acrich series maintains a tolerance of  $\pm 7\%$  on flux and power measurements.

[2]  $\Phi_V$  is the total luminous flux output as measured with an integration sphere.

[3] Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram.

\*Color coordinate:  $\pm 0.01$ , CCT:  $\pm 5\%$

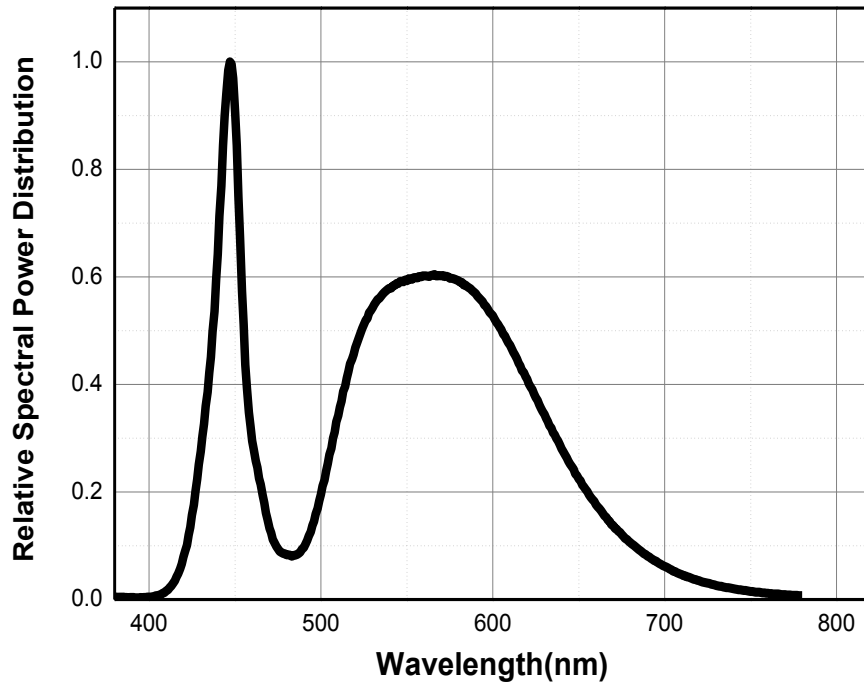
[4] Tolerance is  $\pm 2$  on CRI measurements.

[5] Thermal resistance:  $R\theta_{JS}$  (Junction to Solder)

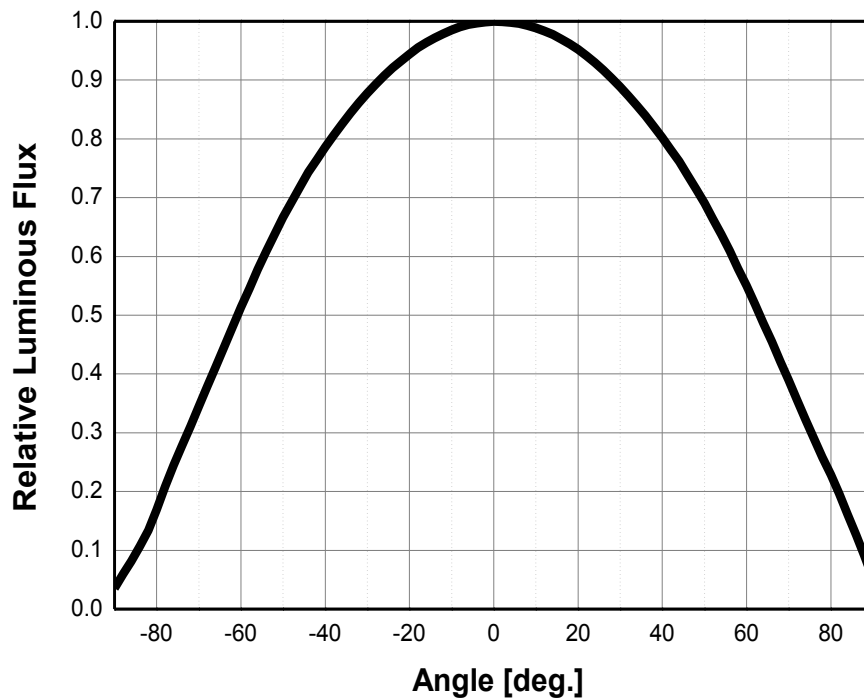
- LED's properties might be different from suggested values like above and below tables if operation condition will be exceeded our parameter range. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
- All measurements were made under the standardized environment of Seoul Semiconductor.

## Characteristics Graph

**Fig 1. Color Spectrum,  $I_F=200\text{mA}$ ,  $T_J=25^\circ\text{C}$**



**Fig 2. Viewing Angle Distribution,  $I_F=200\text{mA}$ ,  $T_J=25^\circ\text{C}$**



## Characteristics Graph

Fig 3. Forward Voltage vs. Forward Current,  $T_j=25^{\circ}\text{C}$

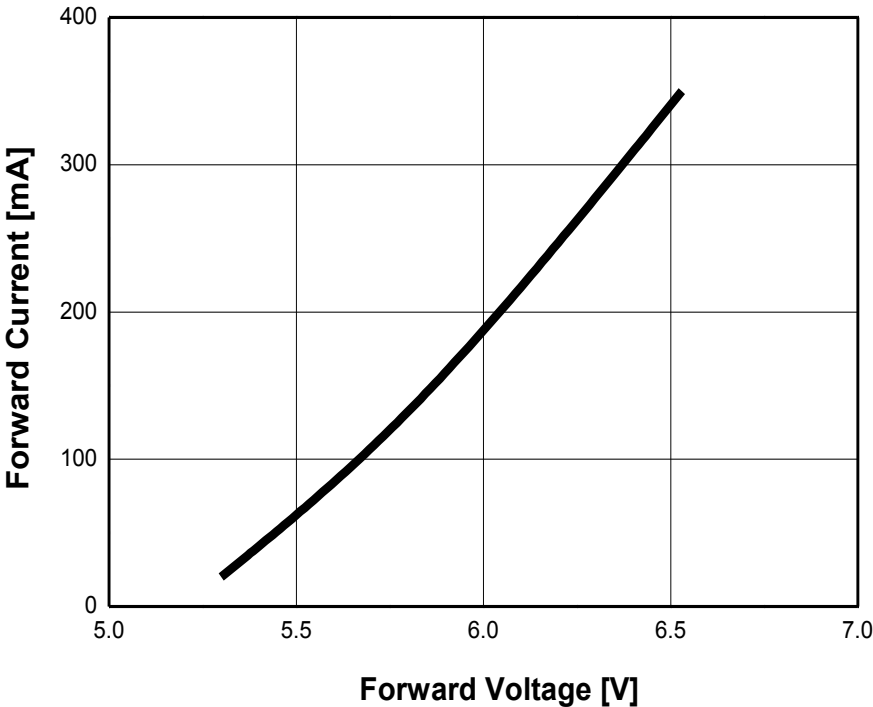
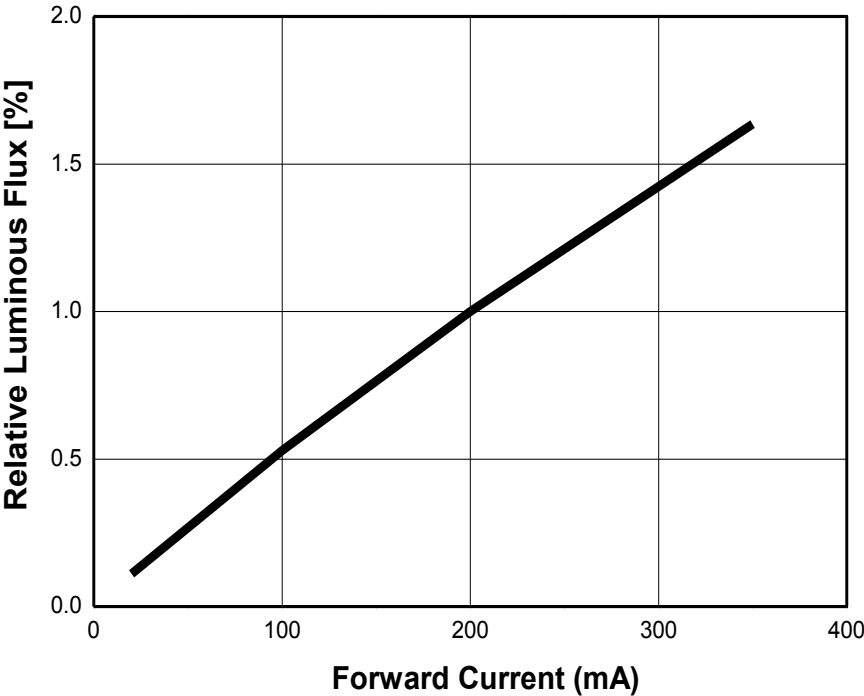
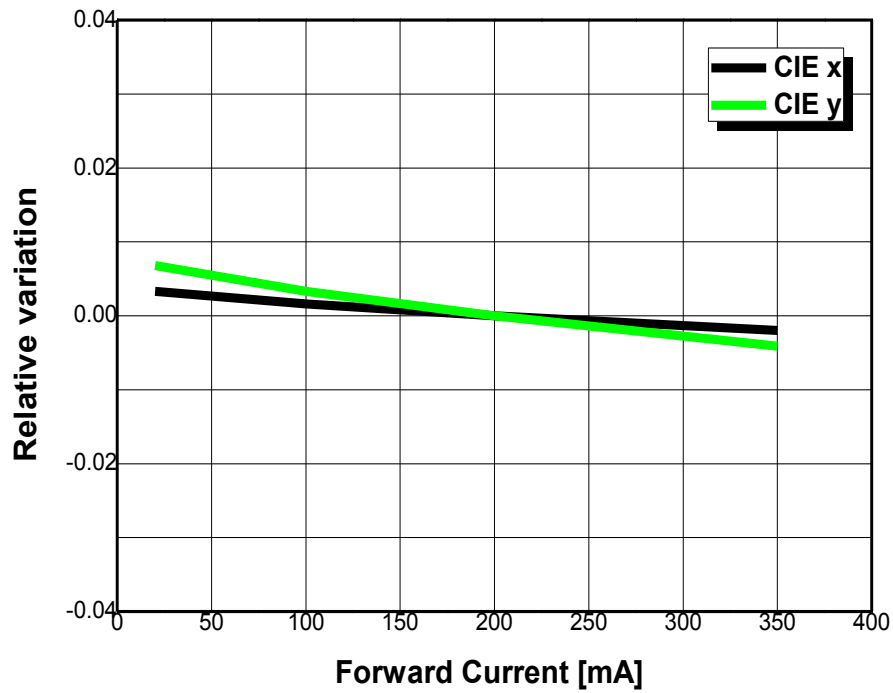


Fig 4. Forward Current vs. Relative Luminous Flux,  $T_j=25^{\circ}\text{C}$



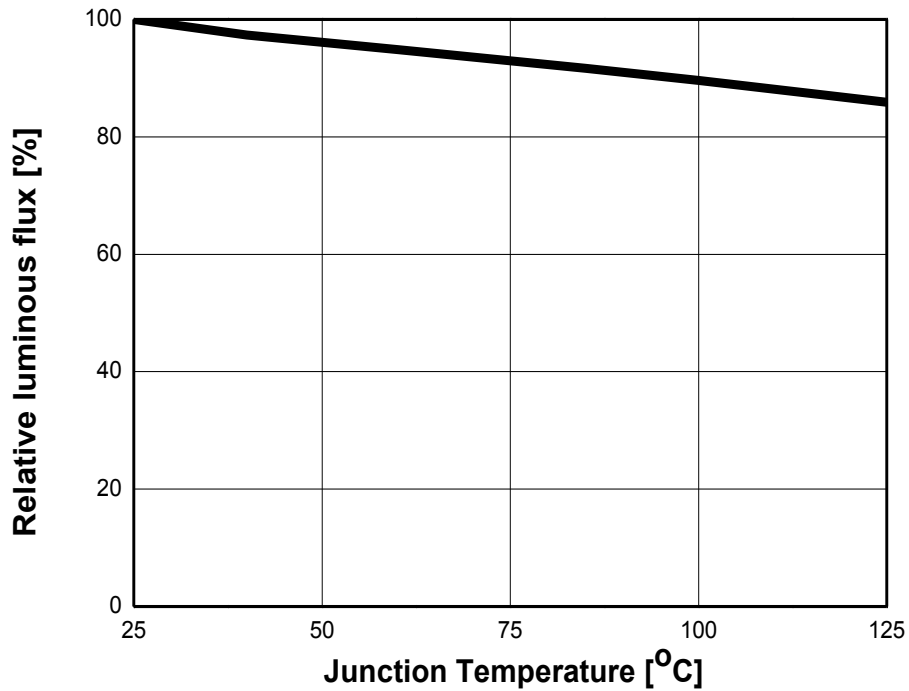
## Characteristics Graph

Fig 5. Forward Current vs. CIE X, Y Shift,  $T_j=25^{\circ}\text{C}$

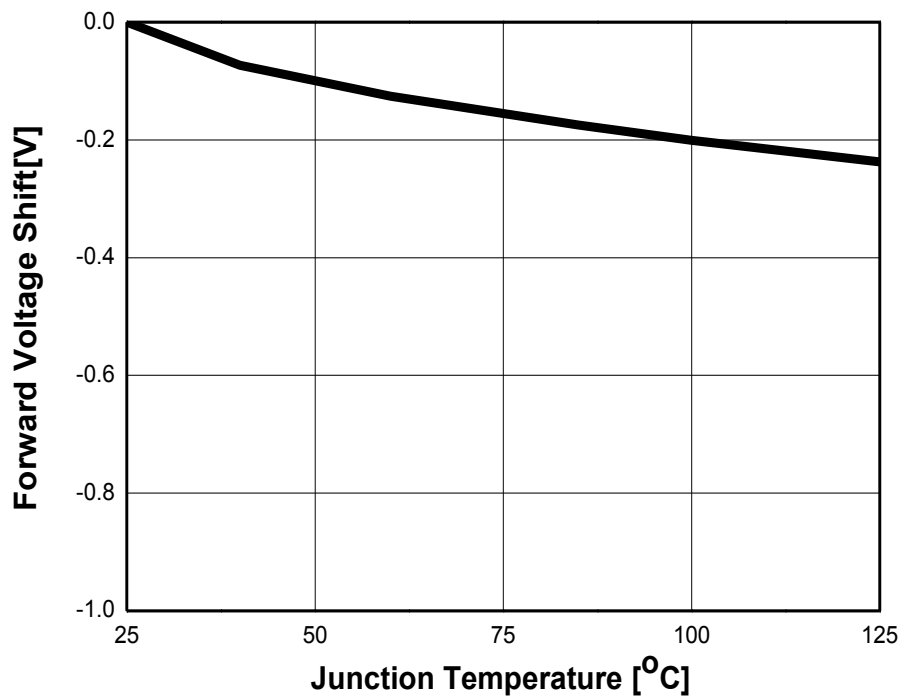


## Characteristics Graph

**Fig 6. Junction Temperature vs. Relative Light Output,  $I_F=200\text{mA}$**

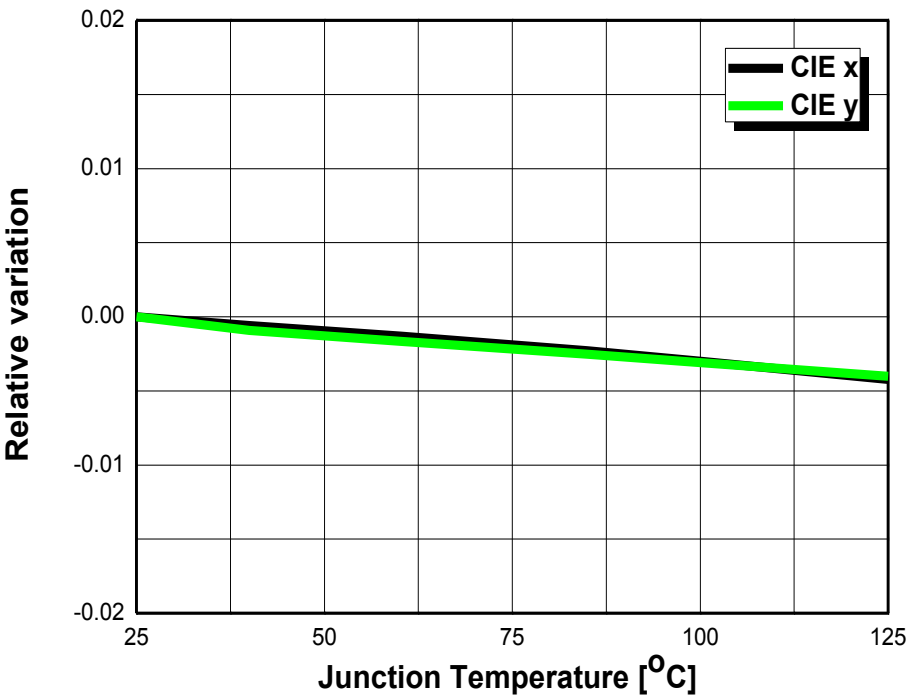


**Fig 7. Junction Temperature vs. Relative Forward Voltage,  $I_F=200\text{mA}$**



# Characteristics Graph

Fig 8. Junction Temperature vs. CIE x, y shift,  $I_F=200\text{mA}$



## Color Bin Structure

**Table 3. Bin Code description,  $I_F = 200\text{mA}$ ,  $T_J = 25^\circ\text{C}$** 

| Part Number          | Luminous Flux (lm) |       |       | Color Chromaticity Coordinate | Forward Voltage ( $V_f$ ) |      |      |
|----------------------|--------------------|-------|-------|-------------------------------|---------------------------|------|------|
|                      | Bin Code           | Min.  | Max.  |                               | Bin Code                  | Min. | Max. |
| SAW09D0A<br>SAW89D0A | W3                 | 177.0 | 188.5 | Refer to page.10              | A                         | 5.6  | 6.2  |
|                      | W4                 | 188.5 | 200.0 |                               | B                         | 6.2  | 6.8  |
|                      | X1                 | 200.0 | 230.0 |                               |                           |      |      |

**Table 4. Luminous Flux rank distribution (SAW09D0A)**

| CCT            | CIE | Flux Rank |    |    |
|----------------|-----|-----------|----|----|
| 7,000 ~ 6,000K | A   | W3        | W4 | X1 |
| 6,000 ~ 5,300K | B   | W3        | W4 | X1 |
| 5,300 ~ 4,700K | C   | W3        | W4 | X1 |

**Table 5. Luminous Flux rank distribution (SAW89D0A)**

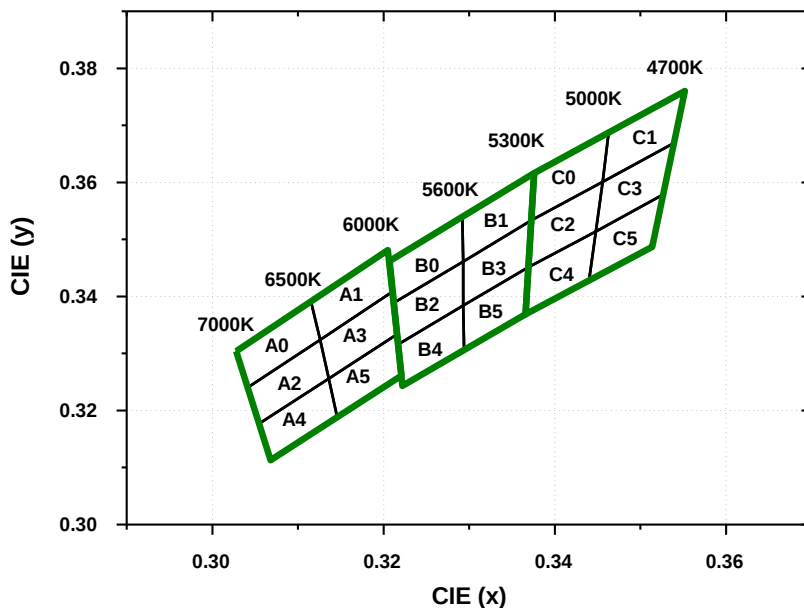
| CCT            | CIE | Flux Rank |    |    |
|----------------|-----|-----------|----|----|
| 7,000 ~ 6,000K | A   | W3        | W4 | X1 |
| 6,000 ~ 5,300K | B   | W3        | W4 | X1 |
| 5,300 ~ 4,700K | C   | W3        | W4 | X1 |



Available ranks  
Not yet available ranks

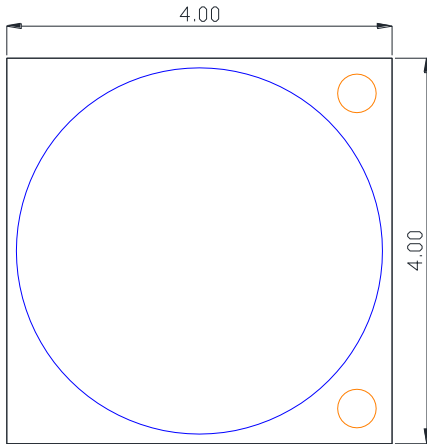
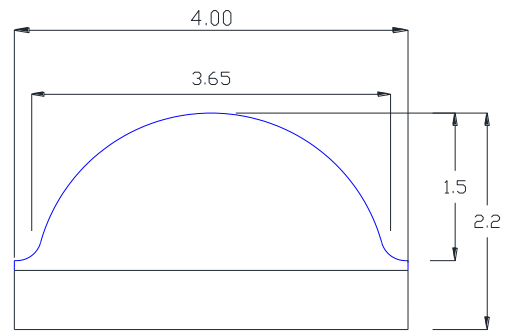
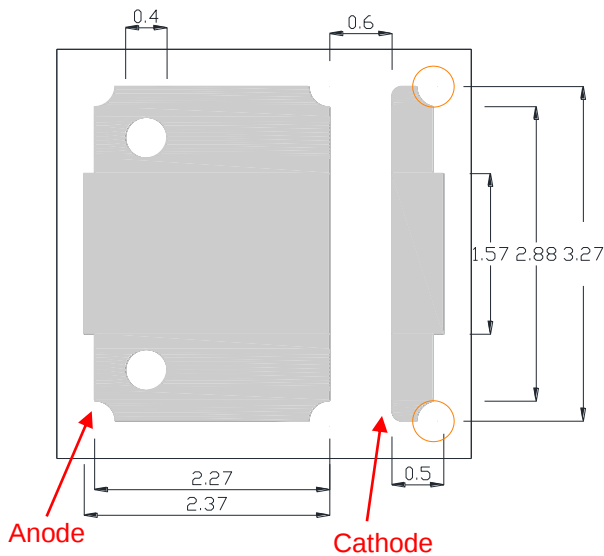
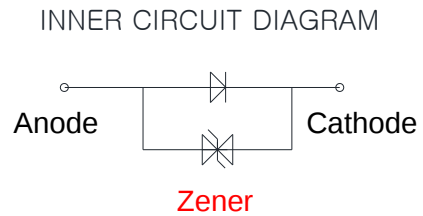
## Color Bin Structure

CIE Chromaticity Diagram (Cool white),  $T_j=25^{\circ}\text{C}$ ,  $I_F=200\text{mA}$



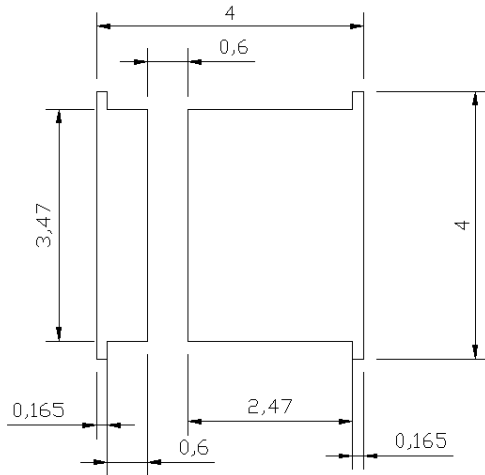
| A0     |        | A1     |        | A2     |        |
|--------|--------|--------|--------|--------|--------|
| CIE x  | CIE y  | CIE x  | CIE y  | CIE x  | CIE y  |
| 0.3028 | 0.3304 | 0.3115 | 0.3393 | 0.3041 | 0.3240 |
| 0.3041 | 0.3240 | 0.3126 | 0.3324 | 0.3055 | 0.3177 |
| 0.3126 | 0.3324 | 0.3210 | 0.3408 | 0.3136 | 0.3256 |
| 0.3115 | 0.3393 | 0.3205 | 0.3481 | 0.3126 | 0.3324 |
| A3     |        | A4     |        | A5     |        |
| CIE x  | CIE y  | CIE x  | CIE y  | CIE x  | CIE y  |
| 0.3126 | 0.3324 | 0.3055 | 0.3177 | 0.3136 | 0.3256 |
| 0.3136 | 0.3256 | 0.3068 | 0.3113 | 0.3146 | 0.3187 |
| 0.3216 | 0.3334 | 0.3146 | 0.3187 | 0.3221 | 0.3261 |
| 0.3210 | 0.3408 | 0.3136 | 0.3256 | 0.3216 | 0.3334 |
| B0     |        | B1     |        | B2     |        |
| CIE x  | CIE y  | CIE x  | CIE y  | CIE x  | CIE y  |
| 0.3207 | 0.3462 | 0.3292 | 0.3539 | 0.3212 | 0.3389 |
| 0.3212 | 0.3389 | 0.3293 | 0.3461 | 0.3217 | 0.3316 |
| 0.3293 | 0.3461 | 0.3373 | 0.3534 | 0.3293 | 0.3384 |
| 0.3292 | 0.3539 | 0.3376 | 0.3616 | 0.3293 | 0.3461 |
| B3     |        | B4     |        | B5     |        |
| CIE x  | CIE y  | CIE x  | CIE y  | CIE x  | CIE y  |
| 0.3293 | 0.3461 | 0.3217 | 0.3316 | 0.3293 | 0.3384 |
| 0.3293 | 0.3384 | 0.3222 | 0.3243 | 0.3294 | 0.3306 |
| 0.3369 | 0.3451 | 0.3294 | 0.3306 | 0.3366 | 0.3369 |
| 0.3373 | 0.3534 | 0.3293 | 0.3384 | 0.3369 | 0.3451 |
| C0     |        | C1     |        | C2     |        |
| CIE x  | CIE y  | CIE x  | CIE y  | CIE x  | CIE y  |
| 0.3376 | 0.3616 | 0.3463 | 0.3687 | 0.3373 | 0.3534 |
| 0.3373 | 0.3534 | 0.3456 | 0.3601 | 0.3369 | 0.3451 |
| 0.3456 | 0.3601 | 0.3539 | 0.3669 | 0.3448 | 0.3514 |
| 0.3463 | 0.3687 | 0.3552 | 0.3760 | 0.3456 | 0.3601 |
| C3     |        | C4     |        | C5     |        |
| CIE x  | CIE y  | CIE x  | CIE y  | CIE x  | CIE y  |
| 0.3456 | 0.3601 | 0.3369 | 0.3451 | 0.3448 | 0.3514 |
| 0.3448 | 0.3514 | 0.3366 | 0.3369 | 0.3440 | 0.3428 |
| 0.3526 | 0.3578 | 0.3440 | 0.3428 | 0.3514 | 0.3487 |
| 0.3539 | 0.3669 | 0.3448 | 0.3514 | 0.3526 | 0.3578 |

## Mechanical Dimensions

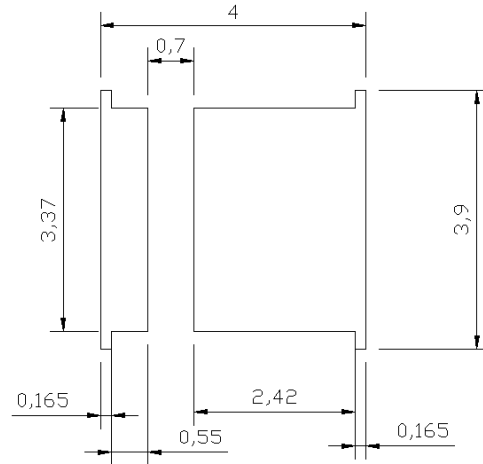
**TOP VIEW**

**SIDE VIEW**

**BOTTOM VIEW**

**CIRCUIT VIEW**

**Notes :**

- (1) All dimensions are in millimeters. (tolerance is  $\pm 0.2\text{mm}$ )
- (2) Scale : none
- (3) The appearance and specifications of the product may be changed for improvement without notice.
- (4) Electrically neutral thermal path.

## Recommended Solder Pad & Metal Mask



**Solder Pad**

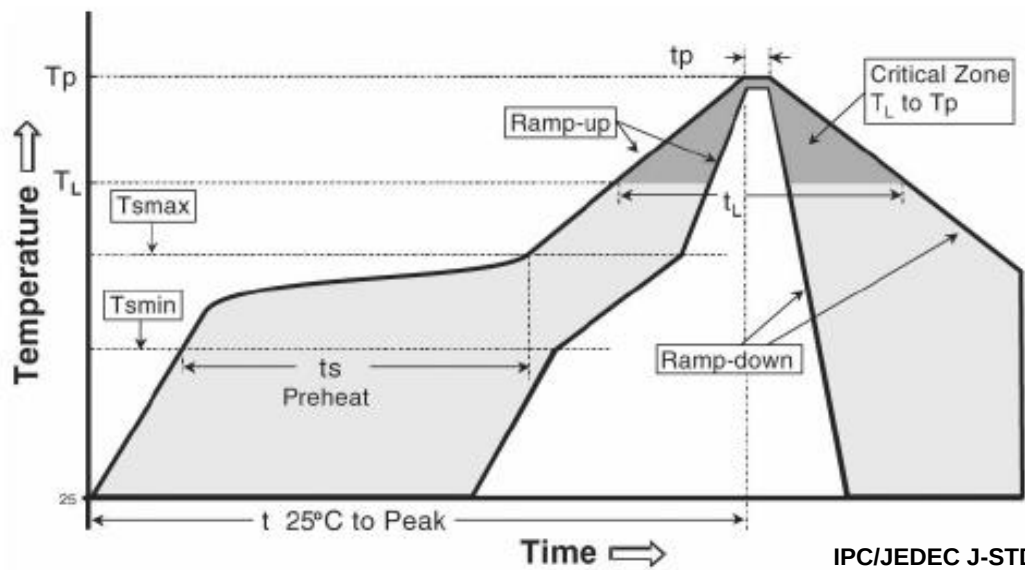


**Metal Mask**

### Notes :

- (1) All dimensions are in millimeters.
- (2) Scale : none
- (3) This drawing without tolerances are for reference only
- (4) Undefined tolerance is  $\pm 0.1\text{mm}$

## Reflow Soldering Characteristics



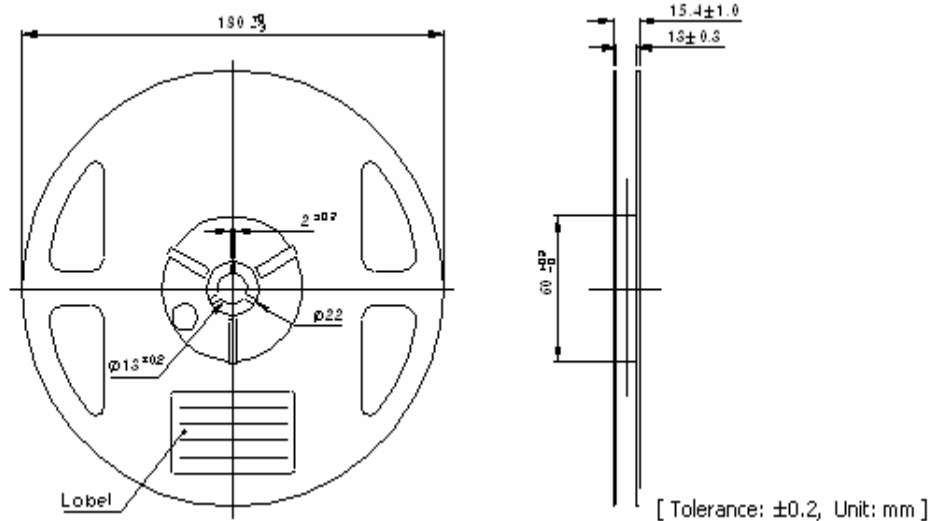
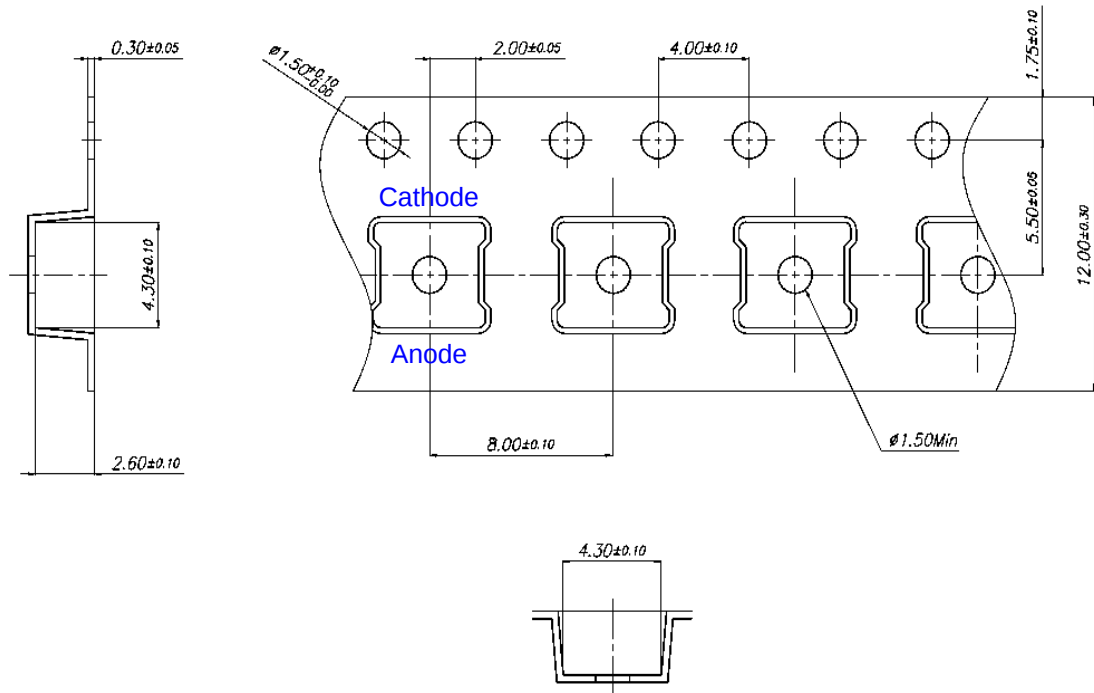
IPC/JEDEC J-STD-020

| Profile Feature                                                                                                                                                                                                                            | Sn-Pb Eutectic Assembly            | Pb-Free Assembly                   |
|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------|------------------------------------|
| Average ramp-up rate ( $T_{smax}$ to $T_p$ )                                                                                                                                                                                               | 3° C/second max.                   | 3° C/second max.                   |
| Preheat <ul style="list-style-type: none"> <li>- Temperature Min (<math>T_{smin}</math>)</li> <li>- Temperature Max (<math>T_{smax}</math>)</li> <li>- Time (<math>T_{smin}</math> to <math>T_{smax}</math>) (<math>t_s</math>)</li> </ul> | 100 °C<br>150 °C<br>60-120 seconds | 150 °C<br>200 °C<br>60-180 seconds |
| Time maintained above: <ul style="list-style-type: none"> <li>- Temperature (<math>T_L</math>)</li> <li>- Time (<math>t_L</math>)</li> </ul>                                                                                               | 183 °C<br>60-150 seconds           | 217 °C<br>60-150 seconds           |
| Peak Temperature ( $T_p$ )                                                                                                                                                                                                                 | 215°C                              | 260°C                              |
| Time within 5°C of actual Peak Temperature ( $t_p$ )2                                                                                                                                                                                      | 10-30 seconds                      | 20-40 seconds                      |
| Ramp-down Rate                                                                                                                                                                                                                             | 6 °C/second max.                   | 6 °C/second max.                   |
| Time 25°C to Peak Temperature                                                                                                                                                                                                              | 6 minutes max.                     | 8 minutes max.                     |

### Caution

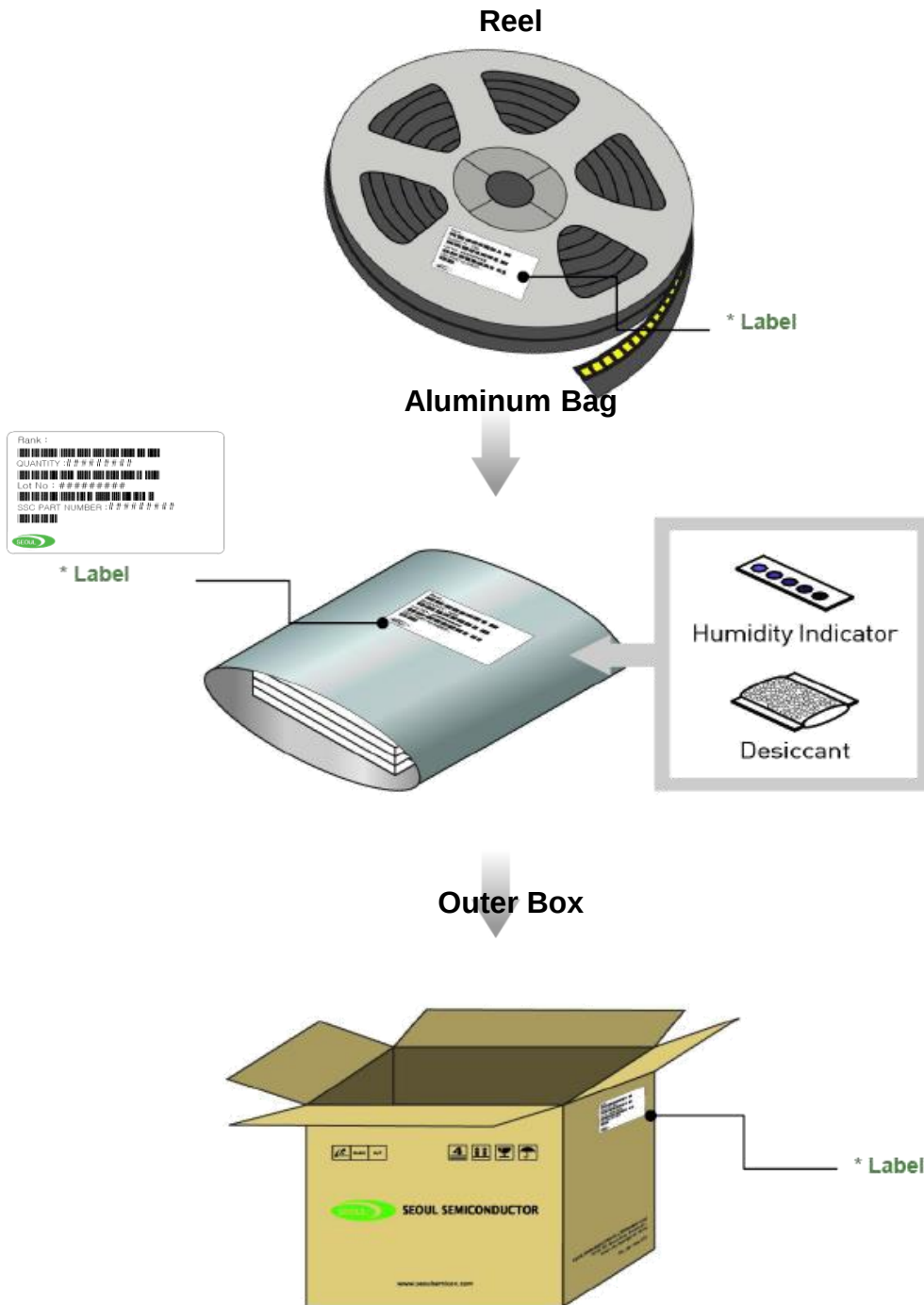
- (1) Reflow soldering is recommended not to be done more than two times. In the case of more than 24 hours passed soldering after first, LEDs will be damaged.
- (2) Repairs should not be done after the LEDs have been soldered. When repair is unavoidable, suitable tools must be used.
- (3) Die slug is to be soldered.
- (4) When soldering, do not put stress on the LEDs during heating.
- (5) After soldering, do not warp the circuit board.

## Emitter Tape & Reel Packaging



- (1) Quantity : 7 inch reel type (700pcs/Reel)
- (2) Cumulative Tolerance : Cumulative Tolerance/10 pitches to be  $\pm 0.2 \text{ mm}$
- (3) Adhesion Strength of Cover Tape.  
Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of  $10^\circ$  to the carrier tape.
- (4) Package : P/N, Manufacturing data Code No. and Quantity to be indicated on a damp proof Package.

## Emitter Tape & Reel Packaging



## Product Nomenclature

**Table 5. Part Numbering System : X<sub>1</sub>X<sub>2</sub>X<sub>3</sub>X<sub>4</sub>X<sub>5</sub>X<sub>6</sub>X<sub>7</sub>X<sub>8</sub>**

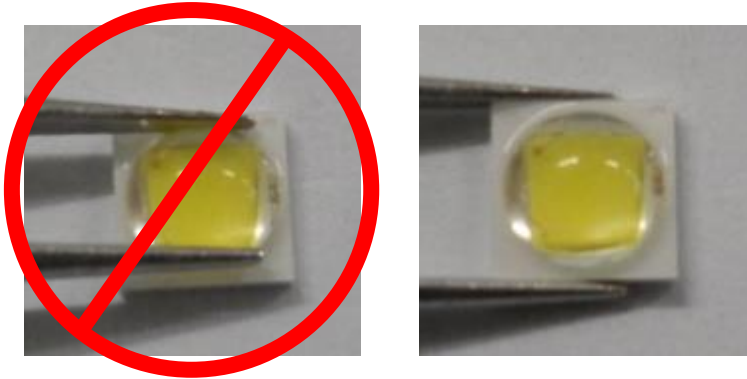
| Part Number Code              | Description         | Part Number | Value                        |
|-------------------------------|---------------------|-------------|------------------------------|
| X <sub>1</sub>                | Company             | S           | SSC                          |
| X <sub>2</sub>                | Acrich LED series   | A           |                              |
| X <sub>3</sub> X <sub>4</sub> | Color Specification | W0<br>W8    | White (Ra70)<br>White (Ra80) |
| X <sub>5</sub>                | Package series      | 9           | 9 series                     |
| X <sub>6</sub>                | Chip                | D           |                              |
| X <sub>7</sub>                | PCB type            | 0           | Emitter                      |
| X <sub>8</sub>                | Revision            | A           | rev0                         |

**Table 6. Lot Numbering System : Y<sub>1</sub>Y<sub>2</sub>Y<sub>3</sub>Y<sub>4</sub>Y<sub>5</sub>Y<sub>6</sub>Y<sub>7</sub>Y<sub>8</sub>Y<sub>9</sub>Y<sub>10</sub>-Y<sub>11</sub>Y<sub>12</sub>Y<sub>13</sub>Y<sub>14</sub>Y<sub>15</sub>Y<sub>16</sub>Y<sub>17</sub>**

| Lot Number Code                                                                                                 | Description         | Lot Number | Value |
|-----------------------------------------------------------------------------------------------------------------|---------------------|------------|-------|
| Y <sub>1</sub> Y <sub>2</sub>                                                                                   | Year                |            |       |
| Y <sub>3</sub>                                                                                                  | Month               |            |       |
| Y <sub>4</sub> Y <sub>5</sub>                                                                                   | Day                 |            |       |
| Y <sub>6</sub>                                                                                                  | Top View LED series |            |       |
| Y <sub>7</sub> Y <sub>8</sub> Y <sub>9</sub> Y <sub>10</sub>                                                    | Mass order          |            |       |
| Y <sub>11</sub> Y <sub>12</sub> Y <sub>13</sub> Y <sub>14</sub> Y <sub>15</sub> Y <sub>16</sub> Y <sub>17</sub> | Internal Number     |            |       |

## Handling of Silicone Resin for LEDs

(1) During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound.



(2) In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

(3) When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented. This is assured by choosing a pick and place nozzle which is larger than the LED's reflector area.

(4) Silicone differs from materials conventionally used for the manufacturing of LEDs. These conditions must be considered during the handling of such devices. Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust.

As mentioned previously, the increased sensitivity to dust requires special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components.

(5) SSC suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin.

Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

(6) Please do not mold this product into another resin (epoxy, urethane, etc) and do not handle this product with acid or sulfur material in sealed space.

## Precaution for Use

### (1) Storage

To avoid the moisture penetration, we recommend store in a dry box with a desiccant . The recommended storage temperature range is 5°C to 30°C and a maximum humidity of RH50%.

### (2) Use Precaution after Opening the Packaging

Use proper SMD techniques when the LED is to be soldered dipped as separation of the lens may affect the light output efficiency.

Pay attention to the following:

#### a. Recommend conditions after opening the package

- Sealing / Temperature : 5 ~ 30°C Humidity : less than RH60%

#### b. If the package has been opened more than 1 year (MSL 2) or the color of the desiccant changes, components should be dried for 10-24hr at 65±5°C

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering.

(4) Do not rapidly cool device after soldering.

(5) Components should not be mounted on warped (non coplanar) portion of PCB.

(6) Radioactive exposure is not considered for the products listed here in.

(7) Gallium arsenide is used in some of the products listed in this publication. These products are dangerous if they are burned or shredded in the process of disposal. It is also dangerous to drink the liquid or inhale the gas generated by such products when chemically disposed of.

(8) This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When washing is required, IPA (Isopropyl Alcohol) should be used.

(9) When the LEDs are in operation the maximum current should be decided after measuring the package temperature.

(10) LEDs must be stored in a clean environment. We recommend LEDs store in nitrogen-filled container.

(11) The appearance and specifications of the product may be modified for improvement without notice.

(12) Long time exposure of sunlight or occasional UV exposure will cause lens discoloration.

## Precaution for Use

(13) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues.

(14) The slug is electrically isolated.

(15) Attaching LEDs, do not use adhesives that outgas organic vapor.

(16) The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

(17) LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). Below is a list of suggestions that Seoul Semiconductor purposes to minimize these effects.

### a. ESD (Electro Static Discharge)

Electrostatic discharge (ESD) is defined as the release of static electricity when two objects come into contact. While most ESD events are considered harmless, it can be an expensive problem in many industrial environments during production and storage. The damage from ESD to LEDs may cause the product to demonstrate unusual characteristics such as:

- Increase in reverse leakage current lowered turn-on voltage
- Abnormal emissions from the LED at low current

The following recommendations are suggested to help minimize the potential for an ESD event. One or more recommended work area suggestions:

- Ionizing fan setup
- ESD table/shelf mat made of conductive materials
- ESD safe storage containers

One or more personnel suggestion options:

- Antistatic wrist-strap
- Antistatic material shoes
- Antistatic clothes

Environmental controls:

- Humidity control (ESD gets worse in a dry environment)

## Precaution for Use

### b. EOS (Electrical Over Stress)

Electrical Over-Stress (EOS) is defined as damage that may occur when an electronic device is subjected to a current or voltage that is beyond the maximum specification limits of the device.

The effects from an EOS event can be noticed through product performance like:

- Changes to the performance of the LED package  
(If the damage is around the bond pad area and since the package is completely encapsulated the package may turn on but flicker show severe performance degradation.)
- Changes to the light output of the luminaire from component failure
- Components on the board not operating at determined drive power

Failure of performance from entire fixture due to changes in circuit voltage and current across total circuit causing trickle down failures. It is impossible to predict the failure mode of every LED exposed to electrical overstress as the failure modes have been investigated to vary, but there are some common signs that will indicate an EOS event has occurred:

- Damaged may be noticed to the bond wires (appearing similar to a blown fuse)
- Damage to the bond pads located on the emission surface of the LED package  
(shadowing can be noticed around the bond pads while viewing through a microscope)
- Anomalies noticed in the encapsulation and phosphor around the bond wires.
- This damage usually appears due to the thermal stress produced during the EOS event.

### c. To help minimize the damage from an EOS event Seoul Semiconductor recommends utilizing:

- A surge protection circuit
- An appropriately rated over voltage protection device
- A current limiting device